JOCDA3BB-L5X Series

Rev.A.1.0

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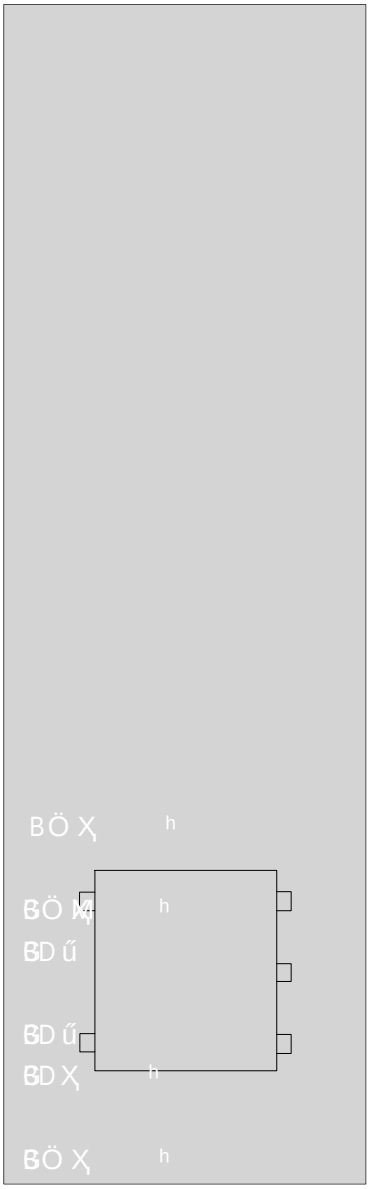
The products are gate driver opto-couplers in LSOP5 and LSOP5W packages. The device consists of an infrared LED optically coupled to an integrated high-gain, high-speed photodetector IC chip. It provides guaranteed performance and specifications at temperature up to 110 . It is physically smaller and compliant with international safety standards for reinforced insulation. It thus provides a smaller footprint solution for applications that require safety standard certification. An internal noise shield provides a guaranteed common-mode transient immunity of ±35 kV/μs. It is ideal for small class IGBT and power MOSFET gate drive. The products are widely used in industrial inverters, IGBT gate drivers, MOSFET gate drivers, induction cooktop and home appliances.



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3A maximum peak output current
High isolation 5000 VRMS
Buffer logic type
Operating temperature range -40°C to 110°C
REACH & RoHS compliance
HBM: H3A; MM: M4; CDM: C3
CQC approved
VDE approved
UL approved

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LED	V_{CC}-V_{EE} (Positive Going)	V_{CC}-V_{EE} (Negative Going)	Output
OFF	0-30V	0-30V	Low
ON	0-6.9V	0-5.9V	Low
ON	6.9V-8.7V	5.9V-7.5V	TRANSITION
ON	8.7V-30V	7.5V-30V	HIGHT

!.{h[¦¢9 a!·la¦a w!¢LbD{ (Temperature=25°C)

Parameter		Symbol	Value	Unit
LED	Forward Current	I_F	50	mA
	Peak Forward Current	I_{FP}	1	A
	Reverse Voltage	V_R	6	V
	Power Dissipation	P_D	100	mW
Detector	Output Voltage	V_O	35	V
	Supply Voltage	V_{CC}	35	V
	Power Dissipation	P_C	400	mW
Isolation Voltage		V_{iso}	5000	Vrms
Operating Temperature		T_{opr}	-40~110	
Junction Temperature		T_j	125	
Storage Temperature		T_{stg}	-55~125	
Total Power Dissipation		P_{tot}	500	mW
Soldering Temperature		T_{sol}	260	

bh¢9M: 100μs pulse, 100Hz frequency
bh¢9H: AC for 1minute, R.H.=40~60%

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	High Level Output Voltage	V_{OH}	I_F=5mA, V_{CC}=10V, I_O=-100mA	6	8.4	-	V
	Low Level Output Voltage	V_{OL}	V_F=0.8V, V_{CC}=10V, I_O=100mA	-	0.3	1	V
	Threshold Input Current	I_{FLH}	V_{CC}=15V, V_O 1V	-	1.2	5	mA
	Threshold Input Voltage	V_{FHL}	V_{CC}=15V, V_O 1V	0.8	-	-	V
	Supply Voltage	V_{CC}	-	10	-	30	V
	UVLO Threshold	VUVLO+	V_O 2.5V, I_F=5mA	7.5	8.7	9.5	V
		VUVLO-	V_O 2.5V, I_F=5mA	7.5	8.4	9.5	V

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Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit
Propagation Delay Time to						

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Characteristics	Symbol	Min.	Typ.	Max.	Unit
Input On-state Current	$I_{F(ON)}$	6.5	-	10	mA
Input Off-state Voltage	$V_{F(OFF)}$	0	-	0.8	V
Supply Voltage	V_{CC}	10	-	30	V
Operating Frequency	f				

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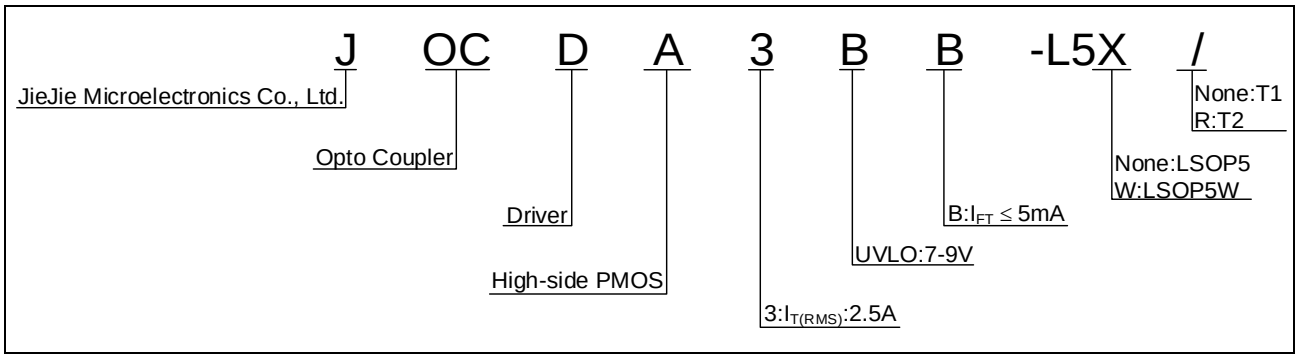

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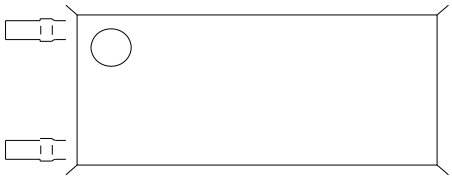

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FIG.1: Forward Current vs. Forward Voltage

FIG.2:

FIG.7: Low-level Output Voltage vs. Ambient Temperature

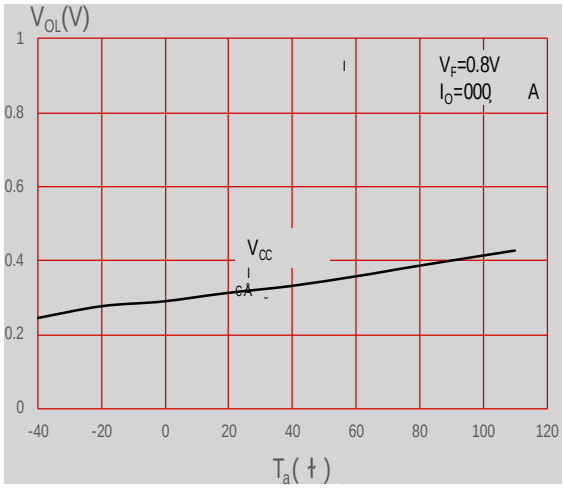
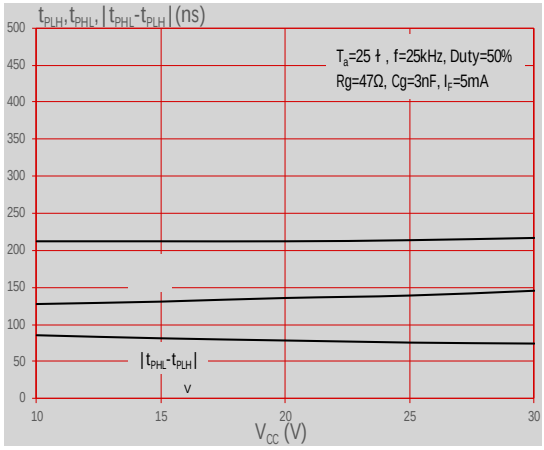


FIG.8: High-level Output Voltage vs. Ambient Temperature

FIG.13: Propagation Delay Time,Pulse Width Distortion vs. Supply Voltage



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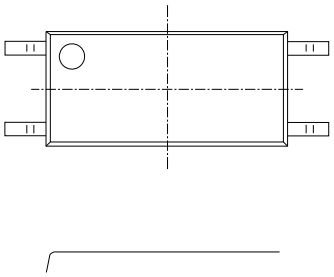

Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	7.40		7.80	0.291		0.307
B	3.40		3.80	0.134		0.150
C	0.00		0.20	0.000		0.008
D	1.80		2.20	0.071		0.087
E	8.10		8.70	0.319		0.343
F	0.40		1.00	0.016		0.039
G	9.90		10.50	0.390		0.413
H	0.10		0.30	0.004		0.012
I	1.80		2.40	0.071		0.094
J	0.25		0.55	0.010		0.022
K						

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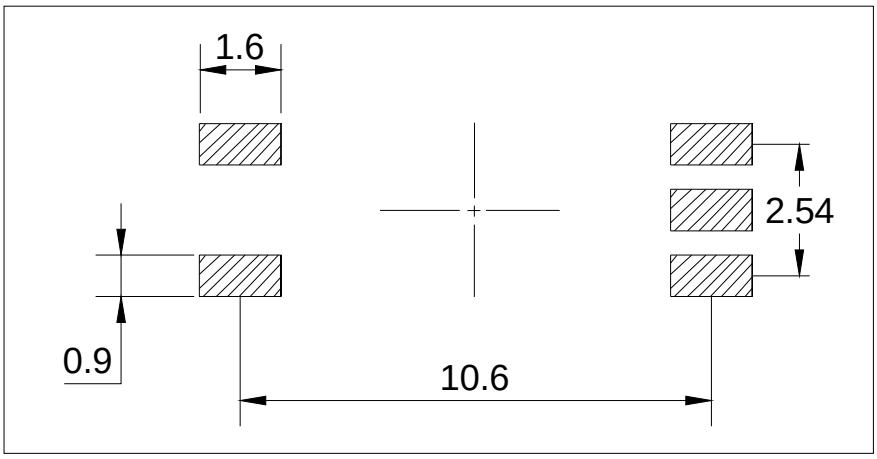

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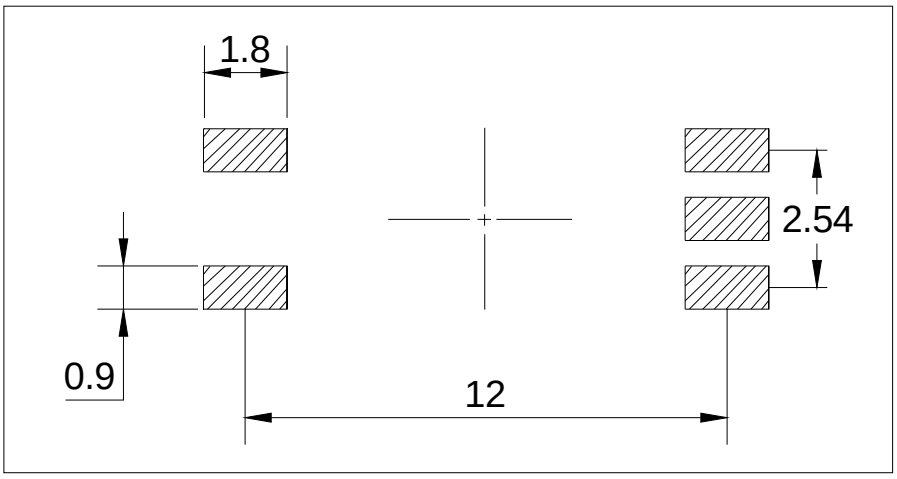

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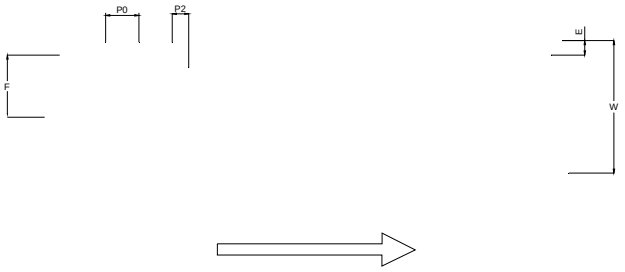

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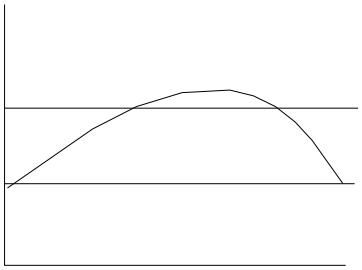

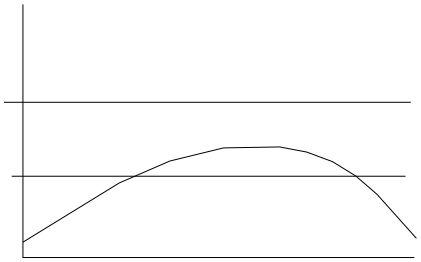

Note:

1. Reflow soldering is recommended at the temperatures and times shown, no more than three times.

2. Avoid direct contact between the epoxy body and any tools or surfaces exceeding its maximum storage temperature.

3. Application of pressure on the epoxy body is prohibited at elevated temperatures. In specific scenarios, any applied force must not exceed 2.5N.

4. Ensure the component has cooled to ambient temperature before proceeding with any subsequent manufacturing steps.

5. The component has a shelf life of one year when stored under1 r o a t a 3 ¥ ’ n